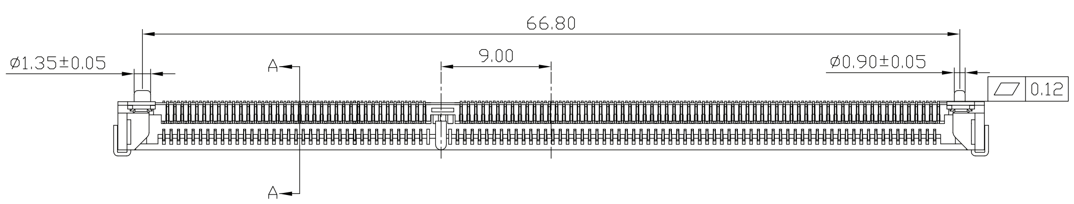
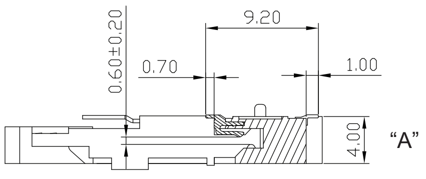
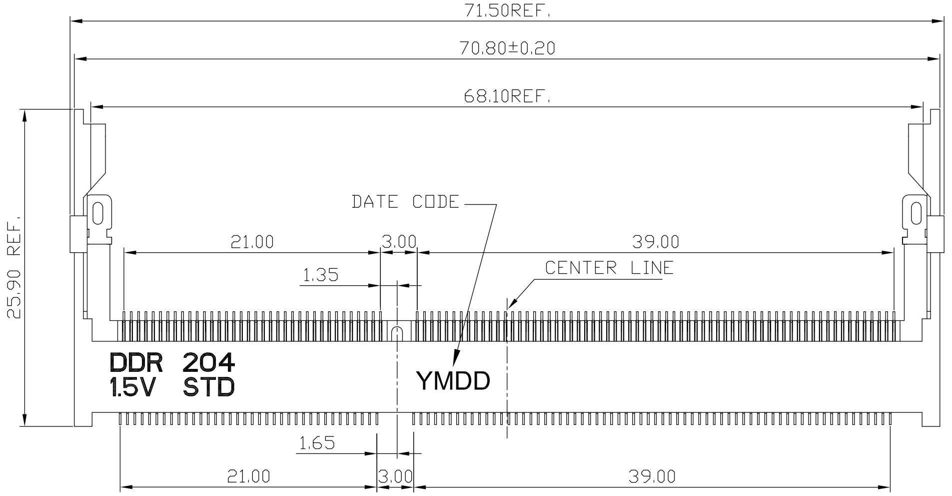
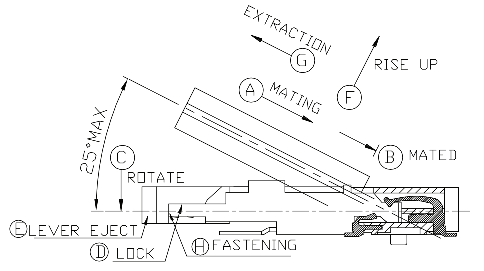




SECTION A-A





HOW TO MATE AND UNMATE

SETP 1.MATE PROCESS Ⓐ→Ⓑ→Ⓒ→Ⓓ
SETP 2.UNMATE PROCESS Ⓔ→Ⓕ→Ⓖ

NOTES:
1. Recommended Reflow Temperature 240˚C
2. Tolerances Non-Cumulative

CONTACT:
Phospher Bronze; Nickel Underplate; Au Flash Overall
With Specified Au Thickness In Contact Area.

MATERIAL:
Housing:High Temperature Thermoplastic, UL94V-0
Metal Latch: Phospher Bronze; Nickel Underplate; Tin Plated Overall

**HOW TO ORDER:**

**B 0 3 0 - 2 0 4 3 - C 0 2 1 - Z**

**NUMBER OF CONTACTS:**
204

**KEY TYPE / VOLTAGE OPTION :**
3 - 1.5V TYPE

**DIM.A OPTION**
6 - 4.0mm

**ORIENTATION:**
0 - Standard

**PLATING OPTIONS:**
2 - Au FLASH

**PACKAGING:**
0 - Tray
1 - Tape & Reel (Normal)
2 - Tape & Reel (Reverse)

**RoHS COMPLIANT**

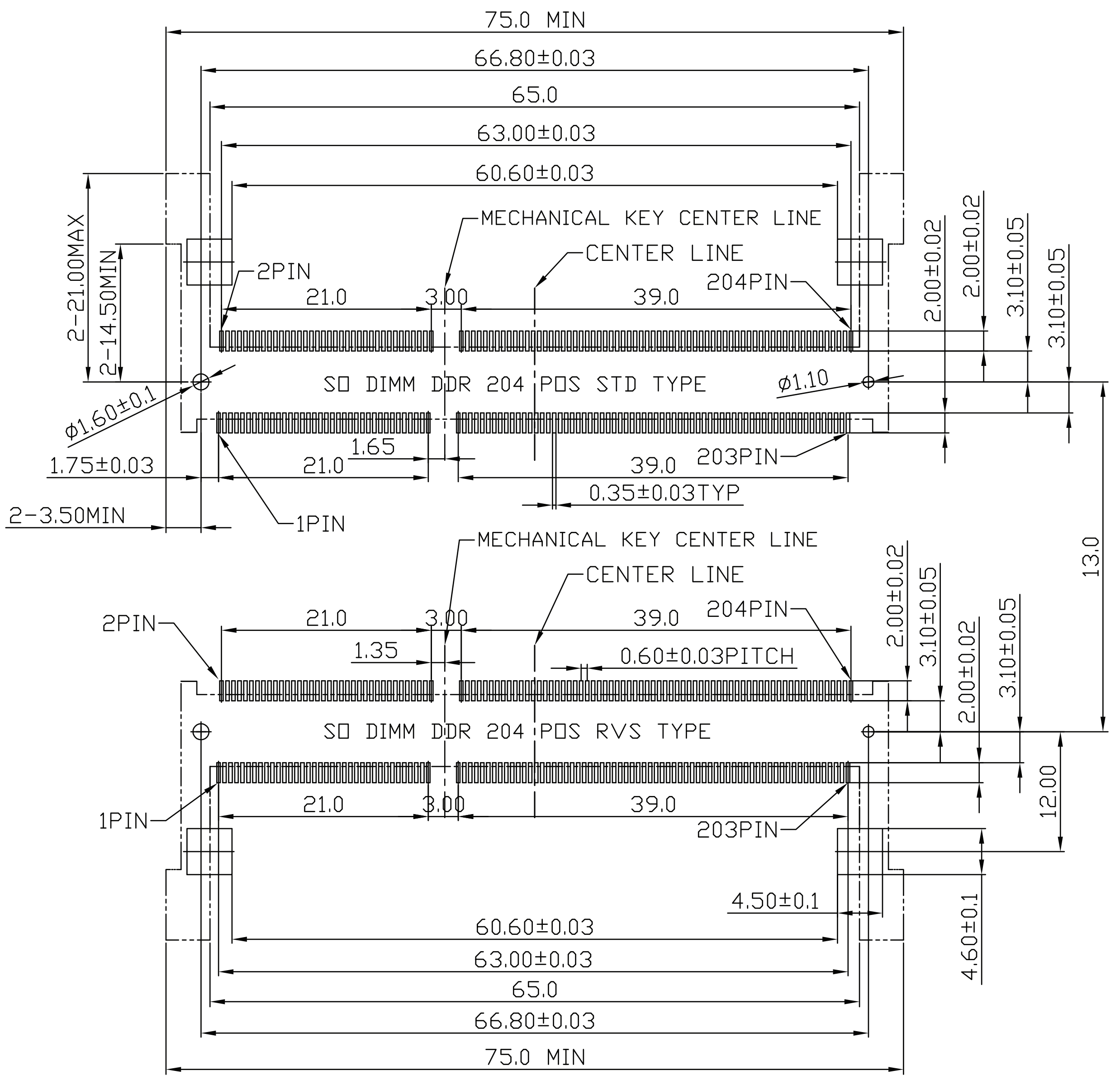
| Rev | Description | Drawn | Checked | Approved | Date |
|---|---|---|---|---|---|
| 0 | Issued | B.S. | S.M. | S.M. | 09/17/09 |
| | | | | | |
| | | | | | |
| | | | | | |

***SMP TECHNOLOGY, INC.***

DDR 3 SO DIMM Socket, 204 Position, Standard Type, Right Angle,
1.5V, 4.0mm Height, Type 2

TOL. DEC. .X +/- 0.30 .XX +/- 0.15 .XXX +/- ANGLE +/- UNIT: mm

P/N: B032-2043-C021-Z



RECOMMENDED P.C.BOARD PATTERN LAYOUT FOR DUAL USE
CONNECTOR MOUNTING SIDE

***SMP TECHNOLOGY, INC.***

DDR 3 SO DIMM Socket, 204 Position, Standard Type, Right Angle,

1.5V, 4.0mm Height, Type 2

P/N: B032-2043-C021-Z

Pg: 2 of 2

TOL. DEC. .X +/- 0.30 .XX +/- 0.15 .XXX +/- ANGLE +/- UNIT: mm